Fig

TITLE: SEMICONDUCTOR PACKAGE WITH INTEGRATED HEAT SPREADER ATTACHED TO A THERMALLY CONDUCTIVE SUBSTRATE CORE
INVENTOR(S): TIMOTHY M. TAKEUCHI
APPLICATION NO.: 10,038,806

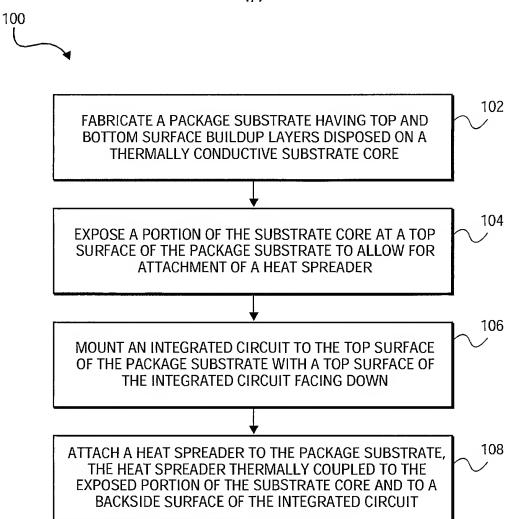
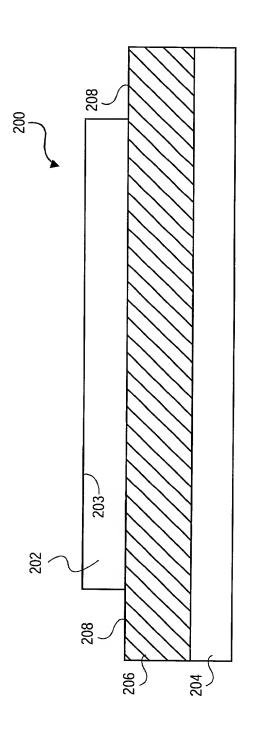


FIG. 1

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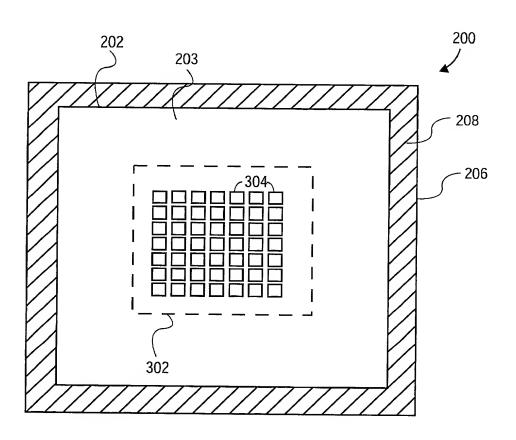
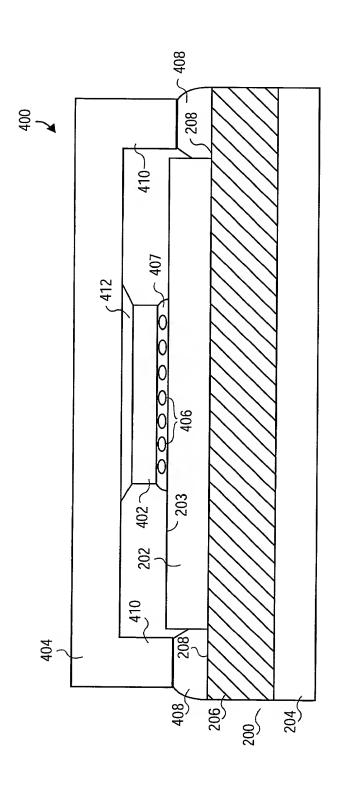


FIG. 3



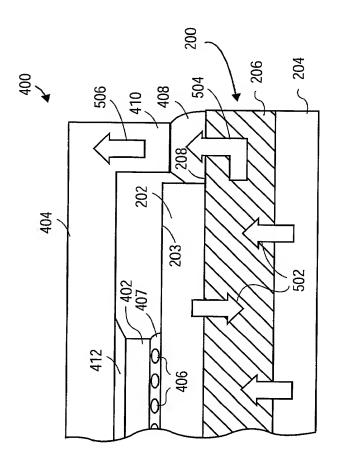
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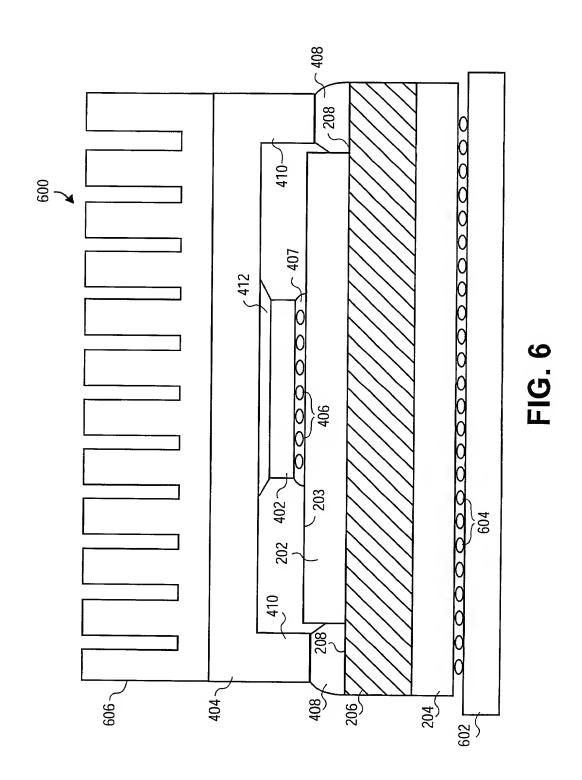




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